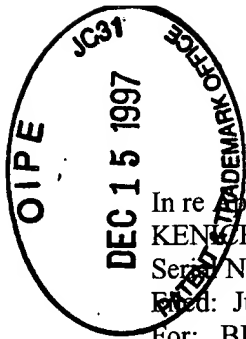


sector



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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

# 3

In re Application of: )  
KENICHI NAKAMURA )  
Serial No. 08/884,778 )  
Filed: June 30, 1997 )  
For: BIODEGRADABLE MOLDING MATERIAL )

BOX MISSING PARTS

LETTER

Hon. Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Dear Sir:

**Certificate of Mailing**  
I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents and Trademarks, Washington, D.C. 20231 on 12-11-97 (date of deposit)  
WILLIAM L. ANDROLIA  
Typed or printed name of person signing this certificate  
Signature [Signature] Dated 12-11-97

In response to the NOTICE TO FILE MISSING PARTS OF APPLICATION dated November 28, 1997 (a copy of which is enclosed) in connection with the above-identified application, Applicant respectfully submits that a signed Declaration and Power of Attorney and check for \$65.00 as the late fee was already sent to the Patent Office on October 27, 1997 along with a signed Assignment and Recordation Cover Sheet and recordation fee of \$40.00. A copy of that complete communication of October 27, 1997 and returned postcard indicating receipt at the Patent Office are enclosed herewith for your information. In addition, Applicant respectfully submits that this application is designated as being of Small Entity status as indicated in the enclosed second page of the above-identified Continuation-In-Part application transmittal page as filed on June 30, 1997. Also enclosed herewith is a copy of the original Statement Claiming Small Entity Status form as filed in the parent application, namely Serial No. 08/770,087.

Applicant therefore respectfully submits that no further documents or fees are required from Applicant at this time.

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WLA/kaq

Respectfully submitted,  
KODA AND ANDROLIA

By: [Signature]  
William L. Androlia  
Reg. No. 27,177